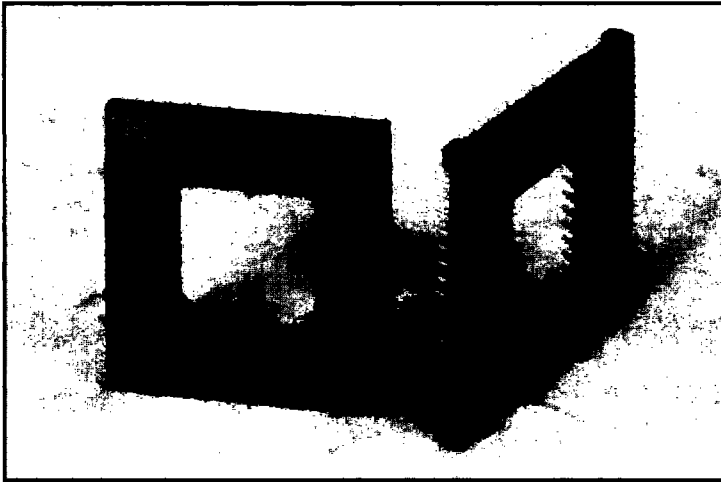


## Interstitial Pin Grid Array Sockets

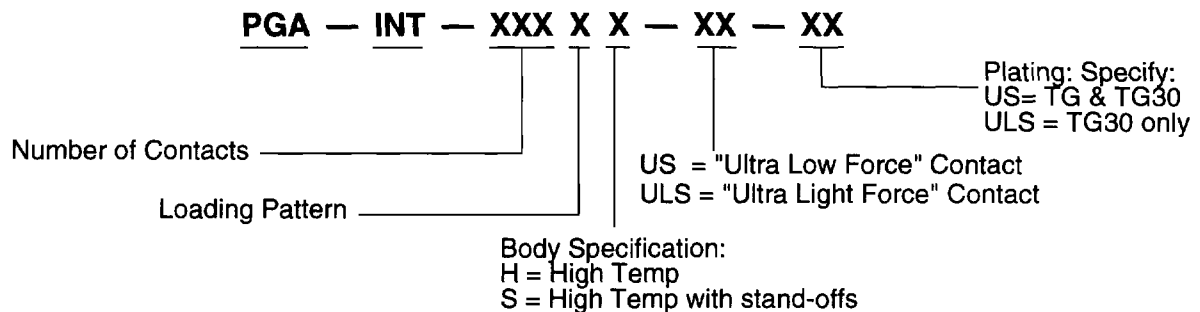
### PGA-INT Series



- .050" staggered design mates with new high density devices
- Molded high temperature body material
  - Suitable for infrared and vapor phase soldering applications
- Screw machine reliability
- Uses RN's ultra-low force contact

SOCKETS

### How to Order PGA-INT Series



#### Materials:

**Body:** High temp, glass filled black polyester,  
**Contact:** Beryllium Copper  
**Shell:** Half Hard Brass

#### Acceptable Pin Sizes:

**Diameter:** .016" - .021" (.41 - .53)  
**Length:** .095" - .145" (2.41 - 3.68)

#### Mounting Information:

**PCB Hole:** .030" ± .002" (.76 ± .05)

**Agency Approvals:** #E73746

#### Performance Characteristics:

**Ultra Low Force Contact (US Lead Style)**  
**Insertion Force:** 1.76 oz\* max per contact  
**Withdrawal Force:** 0.35 oz\* min per contact

**Ultra Light Force Contact (ULS Lead Style)**  
**Insertion Force:** 0.98 oz\* maximum per contact  
**Withdrawal Force:** 0.35 oz\* minimum per contact

\*Based on .018" dia. blunt nose "real life" test pin

**Capacitance:** 1 picofarad minimum  
**Insulation Resistance:** 5000 megohms minimum  
**Dielectric Withstanding Voltage:** 500 volts AC  
**Current Rating:** 1 Ampere/contact  
**Flammability:** UL 94V-0  
**Temperature Range:** -65°C to + 125°C

#### Plating Description:

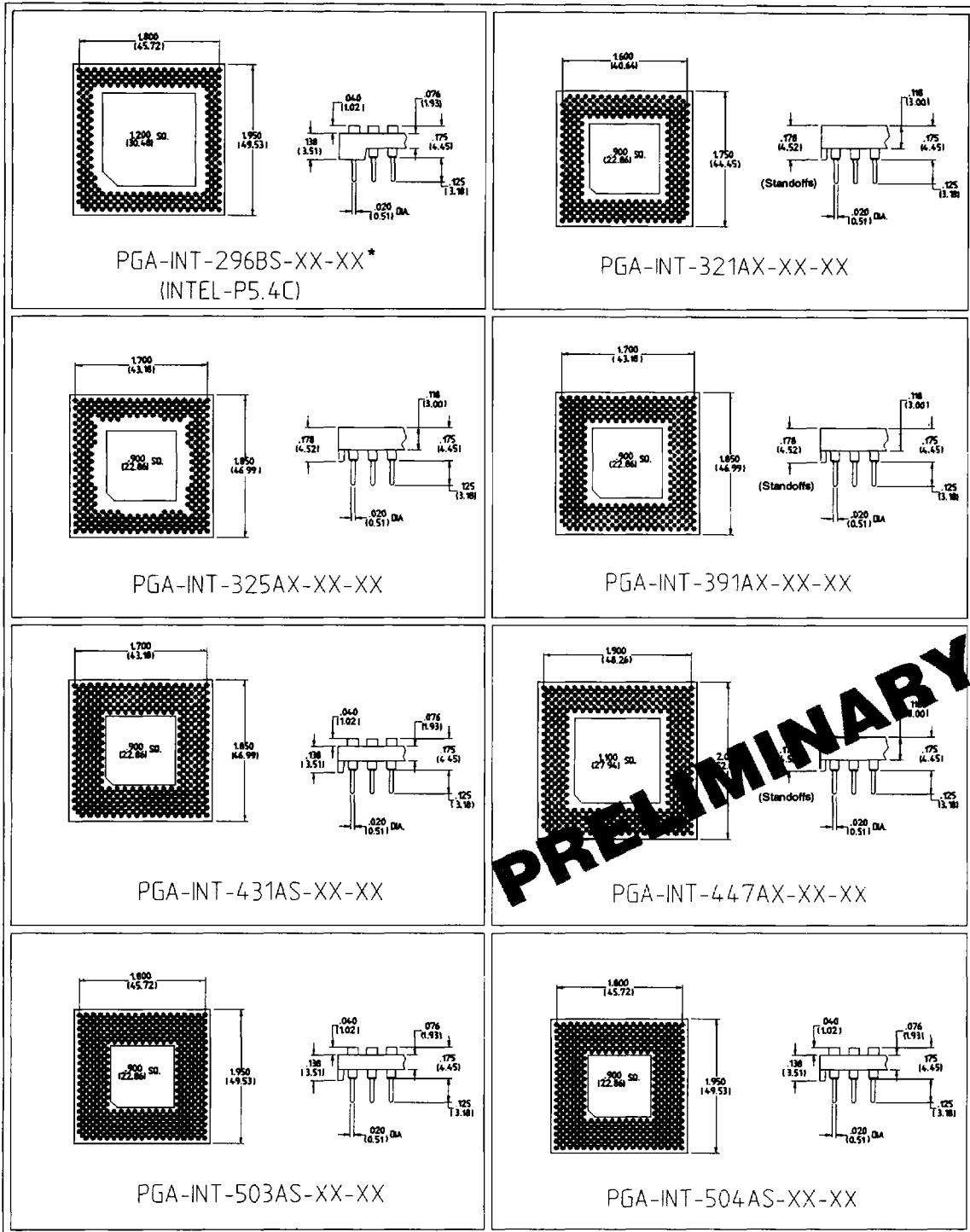
**TG30 =** 30 μinch (.762 μm) minimum  
Gold on contact area  
200 μinch (5.08 μm) minimum  
Tin/Lead on terminal area

**TG =** 10 μinch (.254 μm) minimum  
Gold on contact area.  
200 μinch (5.08 μm) minimum  
Tin/Lead on terminal area.

All options include an Underplate of 50 μinch (1.27 μm) minimum Nickel.

## PGA Interstitial Sockets

### PGA-INT Series



**PRELIMINARY**

SOCKETS

\* Available with Heat Sink Tabs (See PGHS Series)